

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
 QORVO PCB FABRICATION SPECIFICATIONS PCB-21-101.
 A COPY OF PCB-21-101 CAN BE OBTAINED FROM QORVO UPON REQUEST.
 FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 2.

2. ARTWORK FORMAT: GERBER 274X*
 GERBER X2*
 ODB++
 *GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS, PROCESS COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR.

3. MATERIAL:
 NUMBER OF LAYERS: 2 LAYERS
 METAL 1 (TOP) 0.5oz. 1.0oz. 1.5oz. 2.0oz.
 CORE 1: ROGERS 4003C, 0.008in. THICK
 ROGERS 4350B, 0.020in. THICK
 FR4, 0.010in. THICK
 METAL 2 (BOTTOM): 0.5oz. 1.0oz. 1.5oz. 2.0oz.
 SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE), GREEN BLACK BLUE.
 OR LD(LASED DIRECT IMAGEABLE), GREEN BLACK BLUE.
 MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.
 SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.

4. FINISH PLATING:
 METAL 1 (TOP) AND METAL 2 (BOTTOM):
 ENIG (ELECTROLESS NICKEL/IMMERSION GOLD):
 NICKEL PLATE per IPC-4552, 118 - 236µin. (3 - 6µm)
 ELECTROLYTIC FLASH GOLD
 NICKEL PLATE per QQ-N-290, CLASS 1, GRADE G, 200µin. (5µm)
 GOLD PLATE per ASTM B 488, TYPE III, CODE A, 3-10µin. (0.08-0.25µm)
 IMMERSION SILVER per IPC-4553A, (6-18µin.)
 METAL 1 (TOP) SELECTIVE ELECTROLYTIC FLASH GOLD PLATING:
 SELECTIVE ELECTROLYTIC FLASH GOLD PLATE per ASTM B 488, TYPE III, CODE A, CLASS 1, 50µin. (1.27µm)
 PLATING MUST BE FREE FROM CONTAMINATION, STAINS AND DEBRIS.

5. FINISHED BOARD THICKNESS: [0.011in.] Ref.

6. COPPER IS PULLED BACK 0.003in. FROM EDGE OF BOARD ON METAL 1 (TOP) AND METAL 2 (BOTTOM). THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.

7. TOLERANCE: PC BOARD OUTLINE: ±0.003in.

8. BURRS SHALL NOT EXCEED 0.002in.

9. VIA PLATING/FILLING:
 A. ALL VIAS UNDER THE DUT ARE TO BE:
 COPPER-FILLED, OVER-PLATED AND PLANARIZED.
 FINISHED COPPER THICKNESS TO BE 0.0014 ±0.0004in.
 EPOXY-FILLED, (CB100) CONDUCTIVE EPOXY, PLANARIZED.
 B. ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0007in. MIN. THICKNESS.
 C. VIA TYPES AND LAYER ASSOCIATION USED ON BOARD:
 THRU-HOLE VIAS: LAYER: 1-2

10. METAL 1 (TOP) AND METAL 2 (BOTTOM) SHALL BE PLANARIZED AFTER PLATING HOLES SHUT. MAX ALLOWABLE NEGATIVE FEATURE 0.0008in. MAX ALLOWABLE POSITIVE FEATURE 0.0003in.

11. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.

12. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.

13. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.

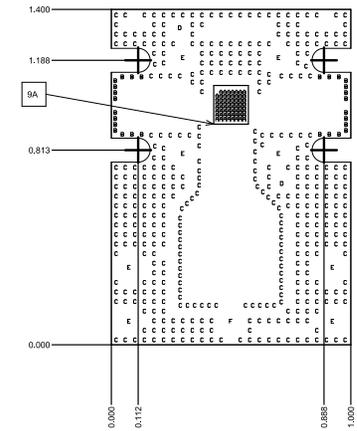
14. NO VENDOR MARKING OR SERIALIZATION ALLOWED.

15. BOARDS SHALL BE SINGULATED AND BAGGED.

16. NO ELECTRICAL TEST NEEDED.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Silkscreen_Top				
2	Soldermask_Top	Solder Resist	1.00mil	0	
3	Metal1_Top	Copper	0.70mil		
4	Dielectric 1	Rogers 4003C	8.00mil	3.38	
5	Metal2_Bot	Copper	0.70mil		

REVISION HISTORY				
ECN	REV	DESCRIPTION	DATE	APPROVAL
ECN-0001549	A	NEW RELEASE	11/05/2015	SKIBBONS



Symbol	Count	Hole Size	Plated	Specified As	Notes
A	63	8.00mil (0.203mm)	PTH	Drill Size	Copper Filled
B	28	15.00mil (0.381mm)	PTH	Drill Size	
C	416	20.00mil (0.508mm)	PTH	Drill Size	
D	2	63.00mil (1.600mm)	NPTH	Finished Size	
E	8	100.00mil (2.540mm)	PTH	Drill Size	
F	1	120.00mil (3.048mm)	PTH	Drill Size	
518 Total					

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES (mm)	PROJECT: TGAXxxx-SM
TOLERANCES .XX = ±.01 .XXX = ±.005 .XXXX = ±.0010	PROJECT: P0000xxx
ANGLES = ±0.5°	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDM
INTERPRET DRAWING PER ANSISAME Y14.5-2009	DESIGNER: A.Byrne 11/05/15
THIRD ANGLE PROJECTION DO NOT SCALE DRAWING	ENGR: D.Allen 11/05/15
	MFG:
	MANAGER: PDM CONTROLLED
	CAGE CODE: 1CVM1

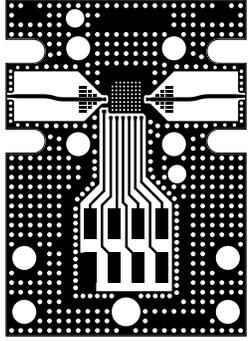
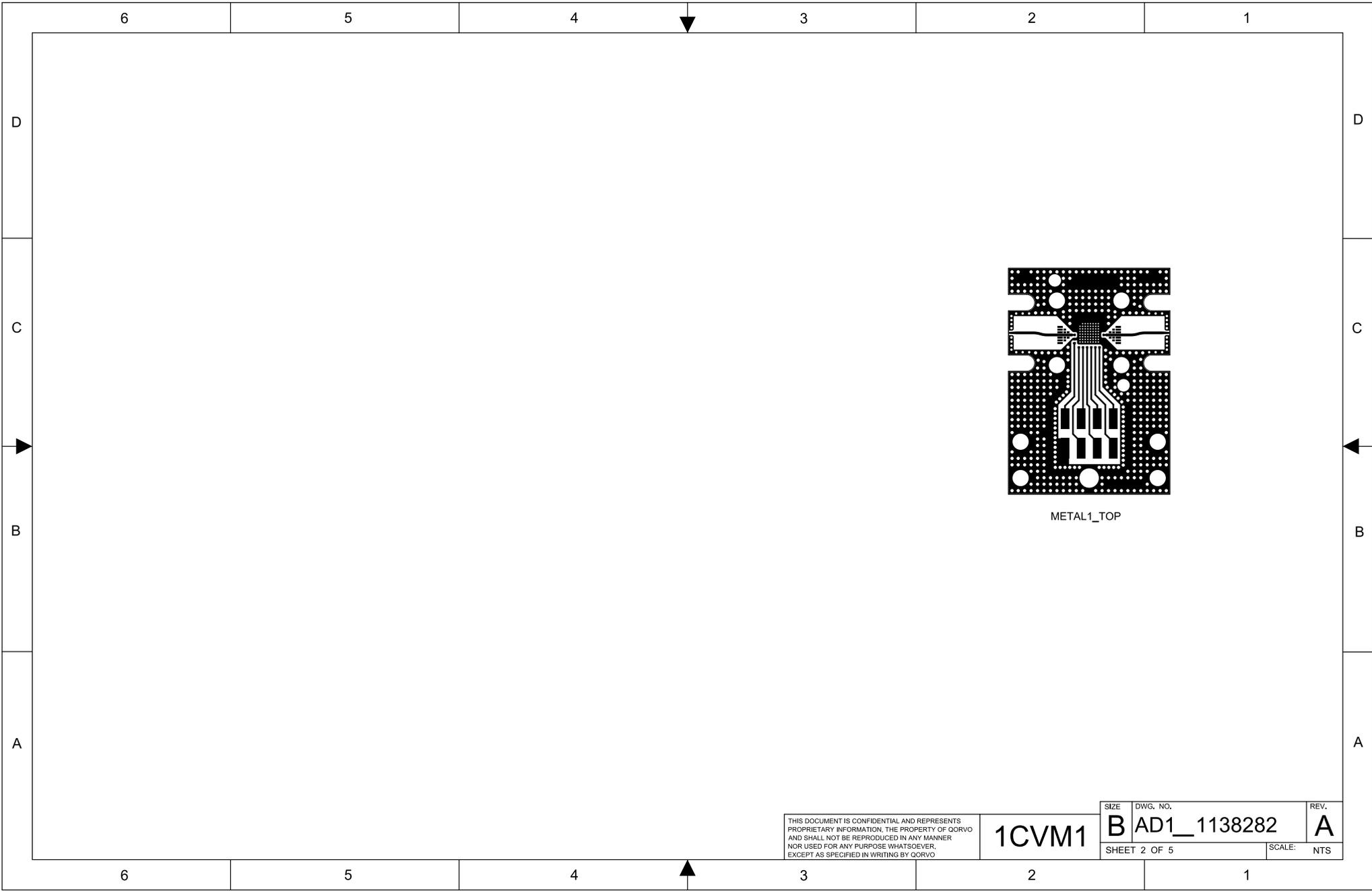
QORVO

TITLE: PCB, TGP2108-SM, SBAND 6BIT PS

SIZE: B DWG. NO. AD1_1138282 REV. A

SHEET 1 OF 5 SCALE: NTS

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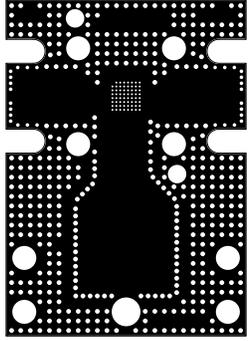
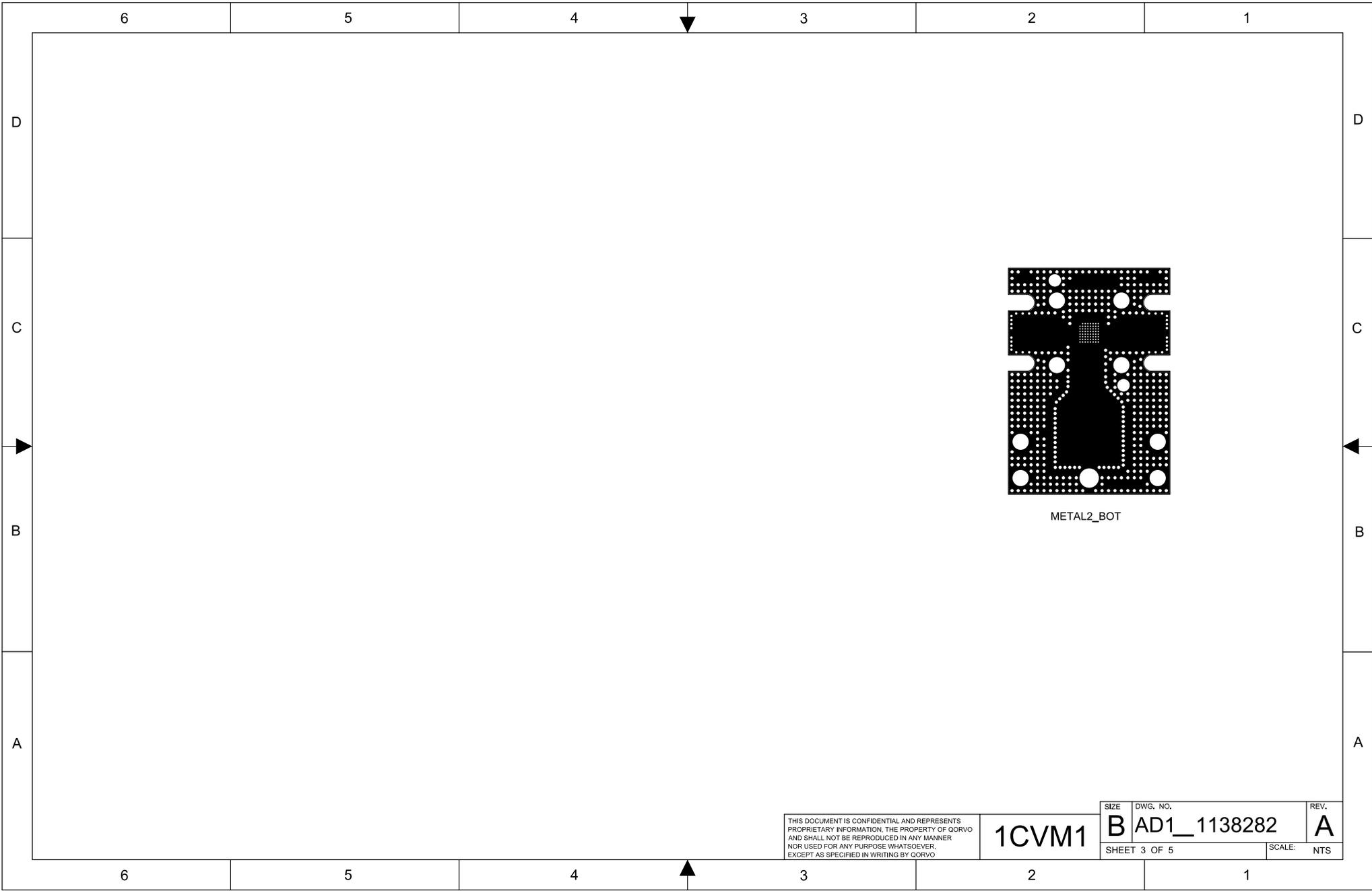


METAL1_TOP

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1CVM1

SIZE	DWG. NO.	REV.
B	AD1_1138282	A
SHEET 2 OF 5		SCALE: NTS

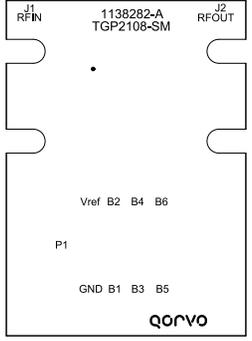
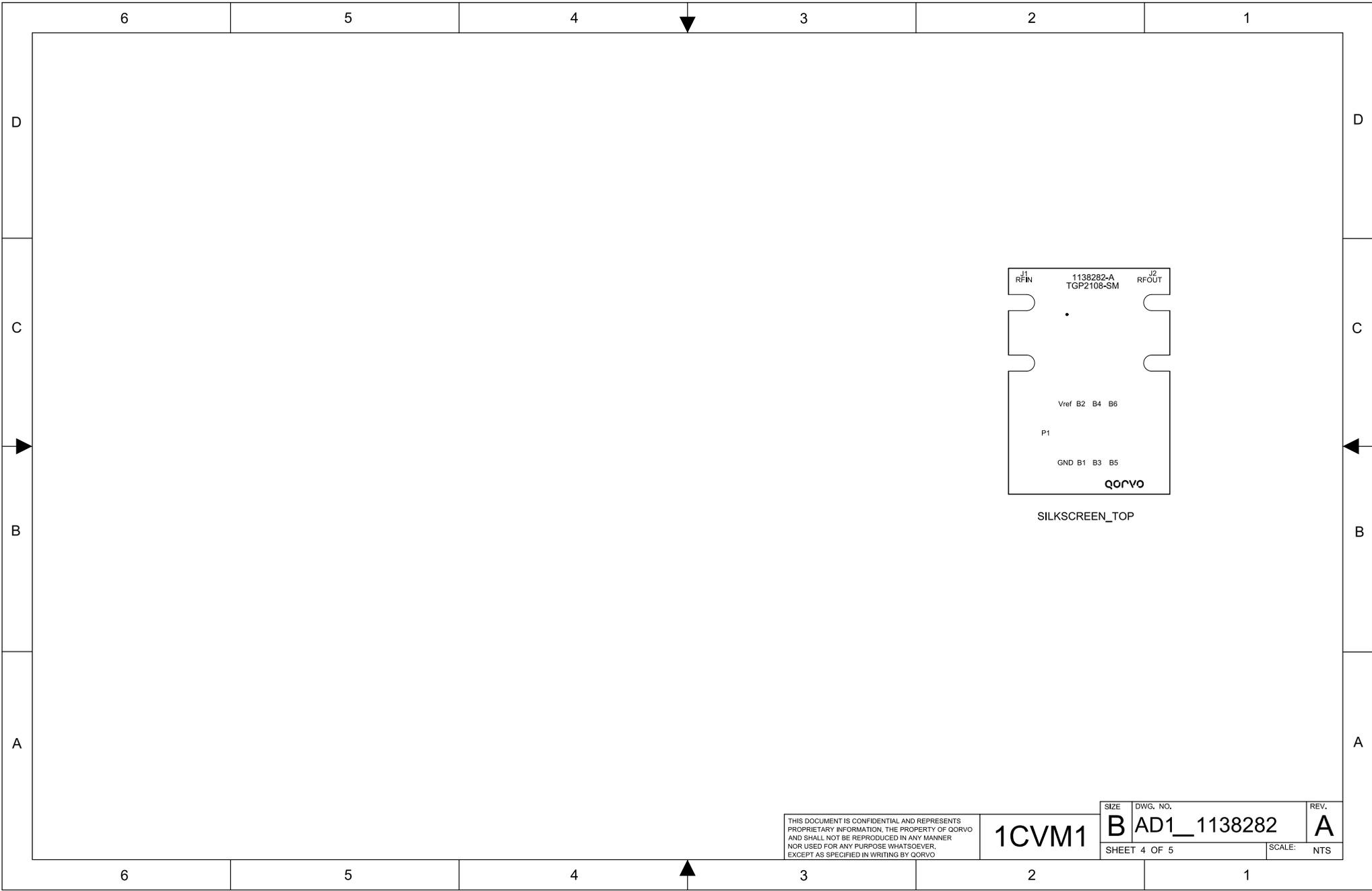


METAL2_BOT

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SIZE	DWG. NO.	REV.
B	AD1_1138282	A
SHEET 3 OF 5		SCALE: NTS

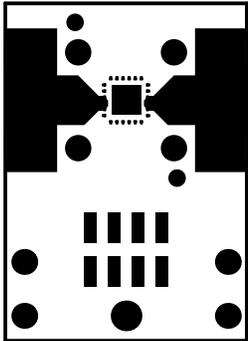
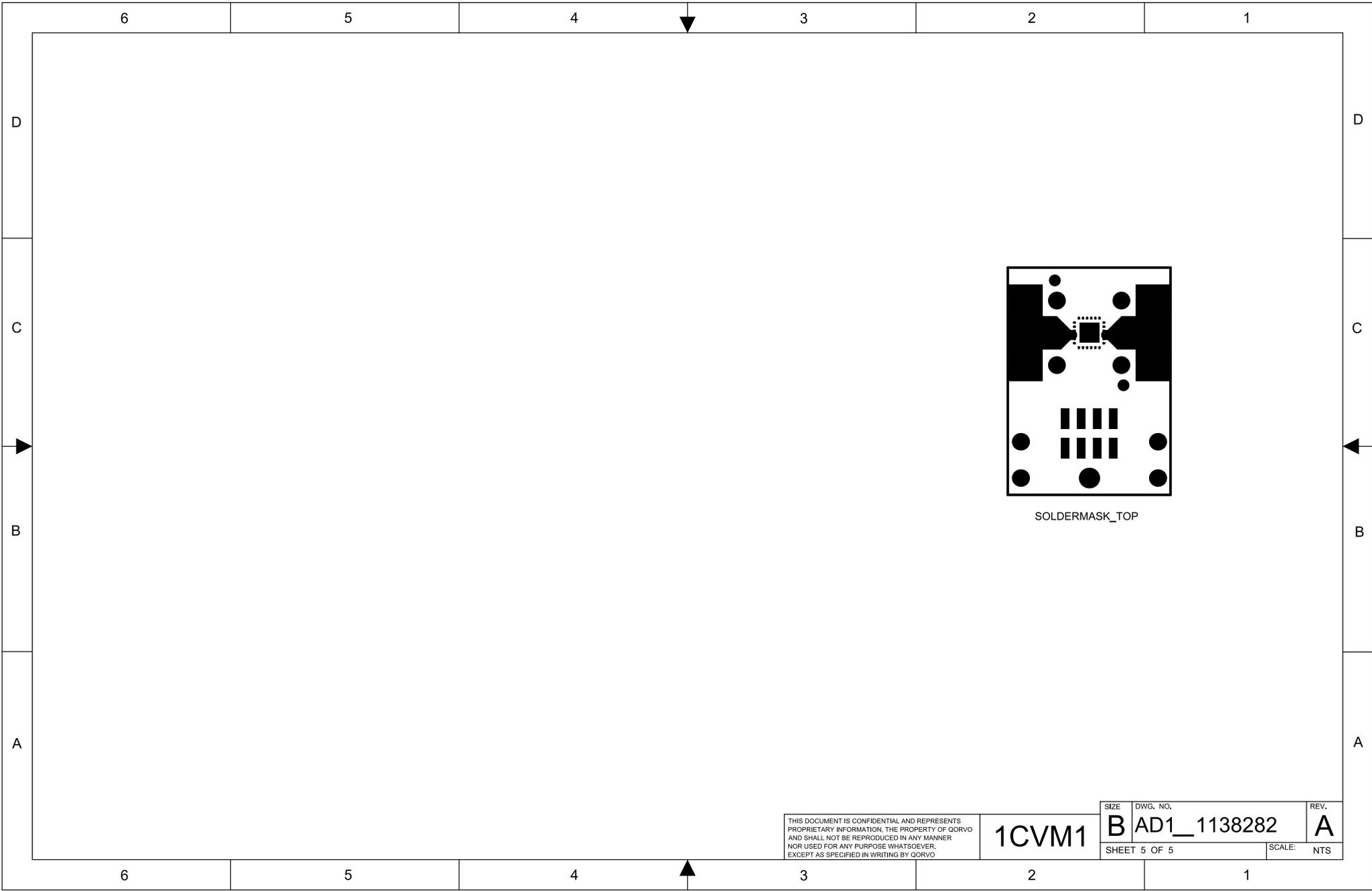


SILKSCREEN_TOP

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SOLDERMASK_TOP

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1CVM1

SIZE	DWG. NO.	REV.
B	AD1_1138282	A
SHEET 5 OF 5		SCALE: NTS